

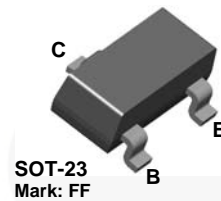


October 2014

# BCV27 NPN Darlington Transistor

## Description

This device is designed for applications requiring extremely high current gain at collector currents to 1.0 A. Sourced from process 05.



## Ordering Information

Part Number	Marking	Package	Packing Method
BCV27	FF	SOT-23 3L	Tape and Reel

## Absolute Maximum Ratings<sup>(1),(2)</sup>

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Value	Unit
$V_{CEO}$	Collector-Emitter Voltage	30	V
$V_{CBO}$	Collector-Base Voltage	40	V
$V_{EBO}$	Emitter-Base Voltage	10	V
$I_C$	Collector Current - Continuous	1.2	A
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

### Notes:

1. These ratings are based on a maximum junction temperature of  $150^\circ\text{C}$ .
2. These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty-cycle operations.

**Thermal Characteristics<sup>(3)</sup>**

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Max.	Unit
$P_D$	Total Device Dissipation	350	mW
	Derate Above $25^\circ\text{C}$	2.8	mW/ $^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	357	$^\circ\text{C}/\text{W}$

**Note:**

3. PCB size: FR-4, 76 mm x 114 mm x 1.57 mm (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.

**Electrical Characteristics**

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CEO}$	Collector-Emitter Breakdown Voltage	$I_C = 10\text{ mA}, I_B = 0$	30			V
$V_{(BR)CBO}$	Collector-Base Breakdown Voltage	$I_C = 10\ \mu\text{A}, I_E = 0$	40			V
$V_{(BR)EBO}$	Emitter-Base Breakdown Voltage	$I_E = 100\ \text{nA}, I_C = 0$	10			V
$I_{CBO}$	Collector Cut-Off Current	$V_{CB} = 30\ \text{V}, I_E = 0$			0.1	$\mu\text{A}$
$I_{EBO}$	Emitter Cut-Off Current	$V_{EB} = 10\ \text{V}, I_C = 0$			0.1	$\mu\text{A}$
$h_{FE}$	DC Current Gain	$I_C = 1.0\ \text{mA}, V_{CE} = 5.0\ \text{V}$	4000			
		$I_C = 10\ \text{mA}, V_{CE} = 5.0\ \text{V}$	10000			
		$I_C = 100\ \text{mA}, V_{CE} = 5.0\ \text{V}$	20000			
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 100\ \text{mA}, I_B = 0.1\ \text{mA}$			1.0	V
$V_{BE(sat)}$	Base-Emitter Saturation Voltage	$I_C = 100\ \text{mA}, I_B = 0.1\ \text{mA}$			1.5	V
$f_T$	Current Gain - Bandwidth Product	$I_C = 30\ \text{mA}, V_{CE} = 5.0\ \text{V},$ $f = 100\ \text{MHz}$		220		MHz
$C_C$	Collector Capacitance	$V_{CB} = 30\ \text{V}, I_E = 0,$ $f = 1.0\ \text{MHz}$		3.5		pF

## Typical Performance Characteristics

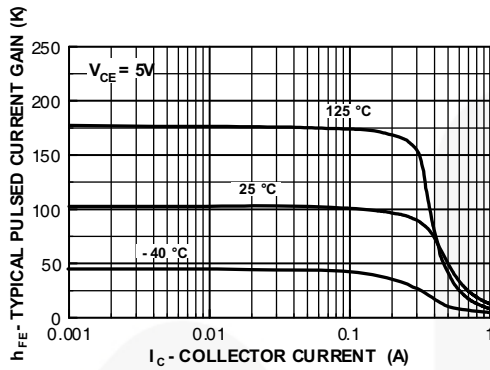


Figure 1. Typical Pulsed Current Gain vs. Collector Current

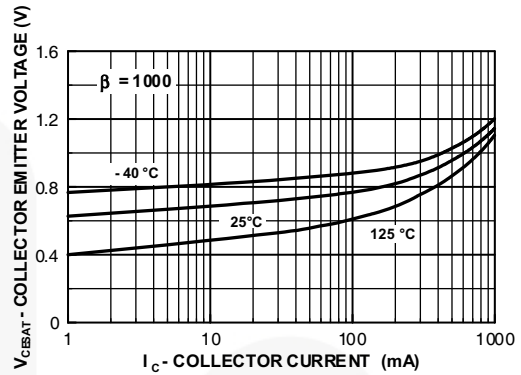


Figure 2. Collector-Emitter Saturation Voltage vs. Collector Current

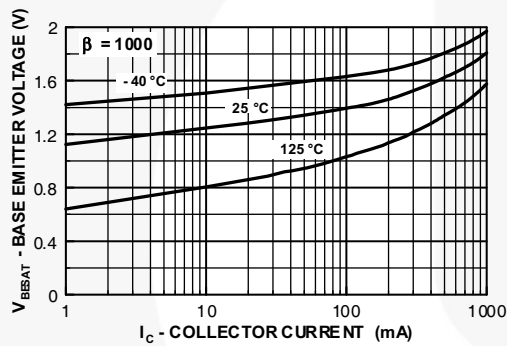


Figure 3. Base-Emitter Saturation Voltage vs. Collector Current

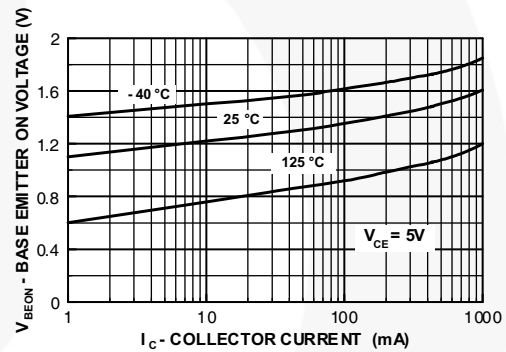


Figure 4. Base Emitter On Voltage vs. Collector Current

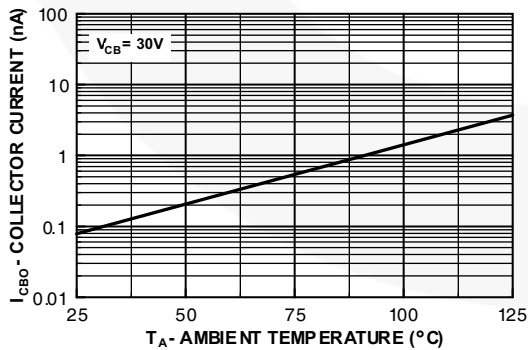


Figure 5. Collector Cut-Off Current vs. Ambient Temperature

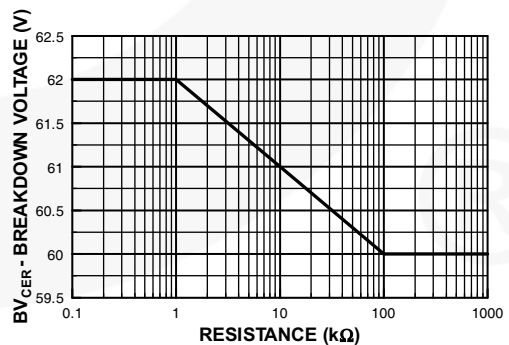


Figure 6. Collector-Emitter Breakdown Voltage with Resistance Between Emitter-Base

Typical Performance Characteristics (Continued)

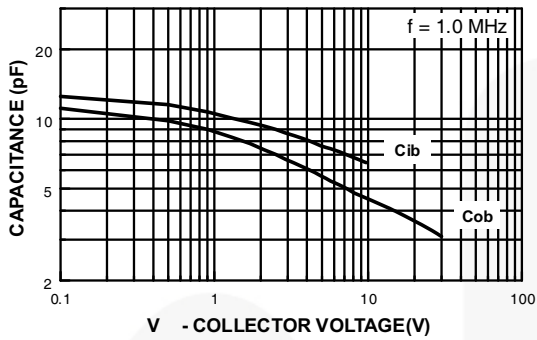


Figure 7. Input and Output Capacitance vs. Reverse Voltage

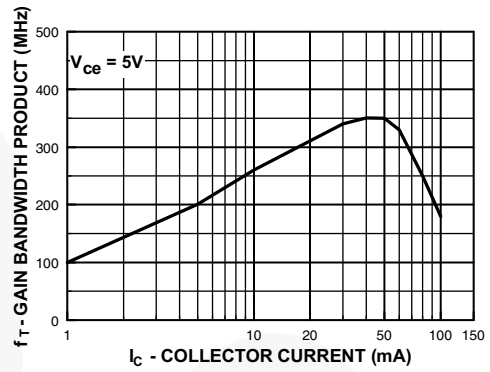


Figure 8. Gain Bandwidth Product vs. Collector Current

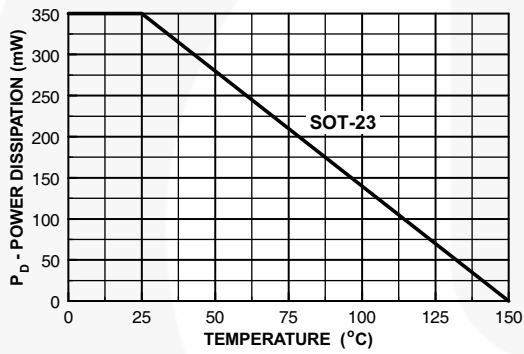
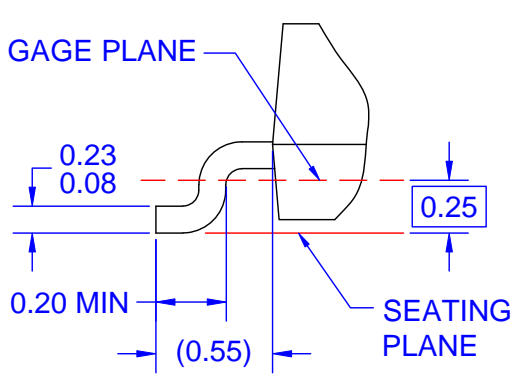
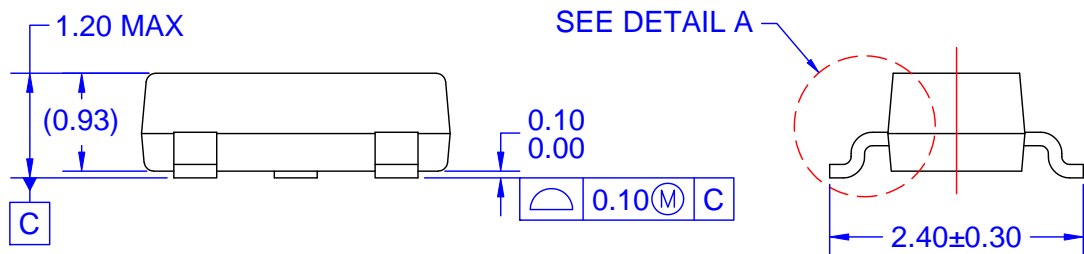
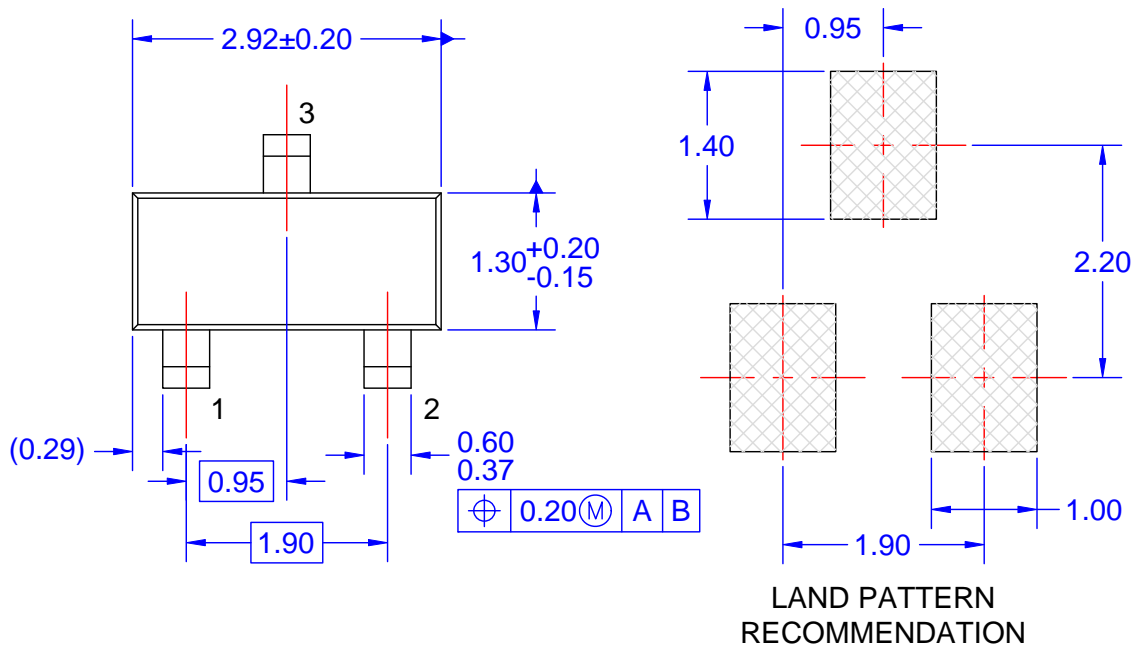


Figure 9. Power Dissipation vs. Ambient Temperature



**DETAIL A**  
 SCALE: 2X

- NOTES: UNLESS OTHERWISE SPECIFIED
- A) REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE H.
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSIONS ARE INCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
  - D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M - 1994.
  - E) DRAWING FILE NAME: MA03DREV10



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